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(71)Applicant : HITACHI LTD
HITACHI VLSI ENG CORP

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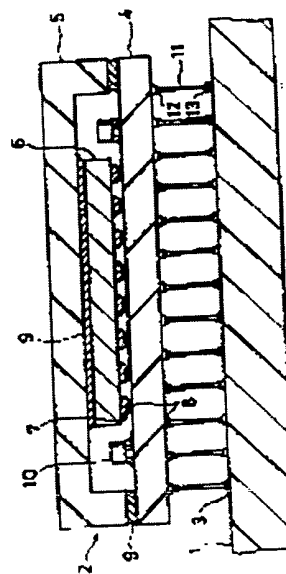
(72)Inventor : OTSUKA KANJI
KATO MASAO
KUMAGAI TAKASHI
USAMI MITSUO
KURODA SHIGEO
SAWARA KUNIZO
YAMADA TAKEO
MIYAMOTO SEIJI
SHIRAI MASAYUKI
OKINAGA TAKAYUKI

(54) SEMICONDUCTOR DEVICE

(57)Abstract:

PURPOSE: To prevent the bonding destruction of a tip end portion of a lead pin by soldering one end of a lead pin with an electrode arranged on the rear of the insulating substrate of a microchip carrier, soldering or brazing the other end with an electrode on the main surface of a printed wiring board, and making the deformation strength of the lead pin smaller than the bonding strength of both ends.

CONSTITUTION: One ends of lead pins 11 are subjected to soldering or brazing with electrodes 8 arranged at specified intervals on the rear of the insulating substrate 4 of a microchip carrier 2. The other ends are subjected to soldering or brazing with the electrodes 8 on the main surface of a printed wiring board 1. The deformation strength of the lead pin 11 is made smaller than the



bonding strength of both ends. As a result, the thermal and mechanical stress caused by thermal mismatching between the insulating substrate 4 of the microchip carrier 2 and the printed wiring board 1 can be relieved by the deformation of the lead pins 11. Thereby the bonding destruction of the end-portions of the lead pins can be prevented.

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